



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR REVERSE DPAK					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	40	20 000	200 °C + N2	0	0.00
HAST	82	8200	130 °C, 85 % RH	0	0.00
Power Cycle	82	1 230 000	DELTA T _j = 100 °C	0	0.00
Pressure Pot	82	7872	121°, 15 PSIG	0	0.00
Solder DUNK	55	165	260 °C, 10 s	0	0.00
Solderability	15	120	883 M2003	0	0.00
Temp. Cycle	82	82 000	- 65 °C to 150 °C	0	0.00